

WCN4-0430WW-C42-F

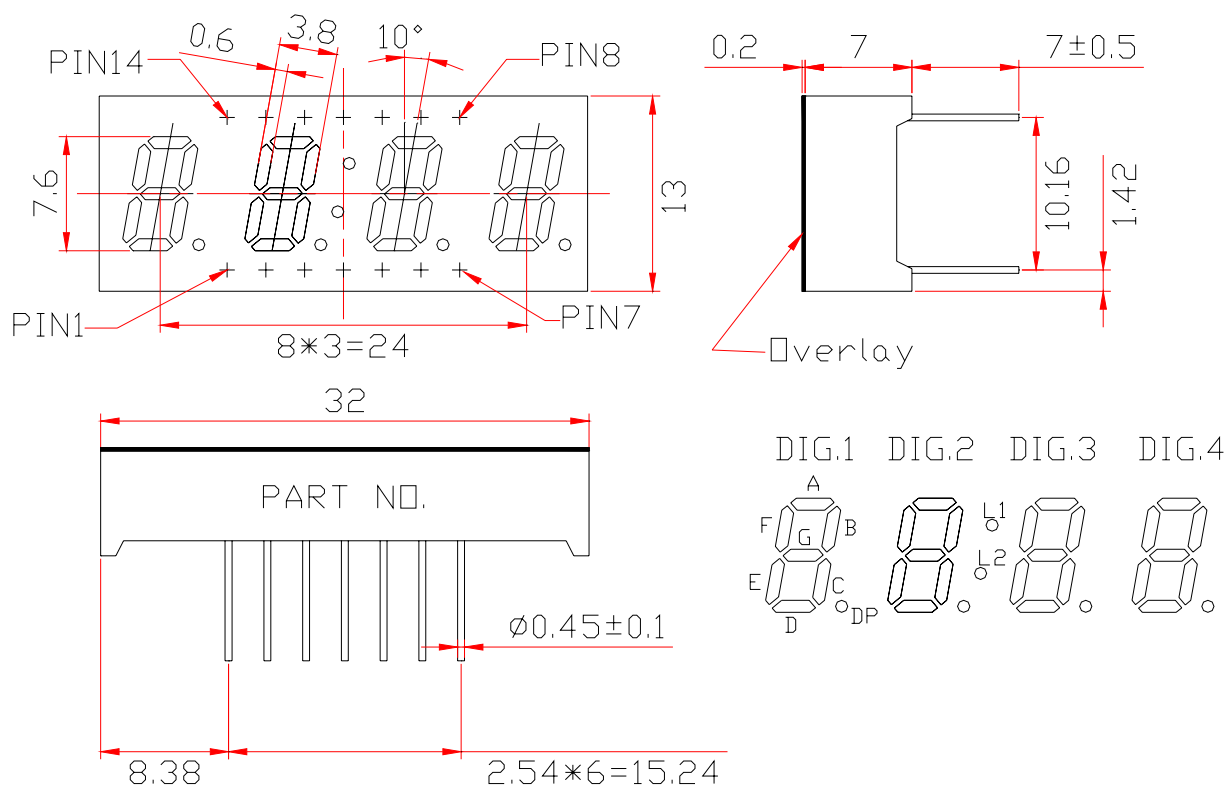
SPECIFICATION

WCN			CUSTOMER Confirmed
Prepared by	Checked by	Approved by	
Fei 2016-7-14	Athena	William	
REVISION RECORD			



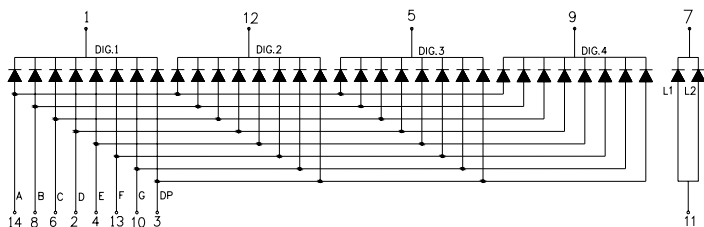
REVISION: A0

■ **Outer Dimension:**



Notes: Unless otherwise stated, the tolerance is $\pm 0.25\text{mm}$.

■ **Circuit Diagram:**



■ **Overlay:**



■ Pin Connection:

PIN NO.	CONNECTION	PIN NO.	CONNECTION
1	Common Cathode Dig.1	8	Anode B
2	Anode D	9	CommonCathode Dig.4
3	Anode DP	10	Anode G
4	Anode E	11	Anode L1,L2
5	Common Cathode Dig.3	12	Common Cathode Dig.2
6	Anode C	13	Anode F
7	Cathode L1,L2	14	Anode A

■ Features:

- High Reliability
- Color: White
- Low Power Requirement
- Easy Assembly

■ Description:

- Four Digit Display
- Digit Height: 7.6mm(0.30")
- Black Face and Yellow Segment with Black Overlay

■ Absolute Maximum Rating (Ta=25°C):

Parameter	Symbol	Condition	Color	Rating	Units
Power Dissipation Per Segment	P _d	—	White	90	mW
Forward Current Per Segment	I _F	—	White	25	mA
Peak Forward Current Per Segment	I _{FP}	1/10 Duty 10KHz	White	100	mA
Reverse Voltage Per Segment	V _R	—	White	5	V
Operating Temperature Range	T _{opr}	—	—	-35~+85	°C
Storage Temperature Range	T _{stg}	—	—	-35~+85	°C

■ Electrical/Optical Characteristics Rating(Ta=25°C)

Item	Symbol	Test conditions	Location	Rating			Units
				Min.	Typ.	Max.	
Forward Voltage	V _F	I _F =20mA	Per Segment	2.6	3.0	3.6	V
Reverse Current	I _R	V _R =5V	Per Segment	—	—	100	μA
Luminous Intensity	I _V	I _F =10mA	Per Segment	4001	6500	10500	μcd
Peak Emission Wave Length	λ _P	I _F =20mA	Per Segment	—	0.270	—	nm
	λ _D			—	0.300	—	
Spectral Line Half Width	△λ	I _F =20mA	Per Segment	—	20	—	nm
Luminous Intensity Matching Ratio (Segment to Segment)	I _{v-m}	I _F =10mA	—	—	—	1.2:1	

LED Displays Reliability Test:

CLASSIFICATION	TEST ITEM	DESCRIPTION AND TEST CONDITION
ENDURANCE TEST	OPERATION LIFE	EVALUATES RESISTANCE OF THE DEVICE WHEN OPERATED AT ELECTRICAL STRESS T _a = UNDER ROOM TEMPERATURE I _F = I _F max
	HIGH TEMPERATURE HIGH HUMIDITY STORAGE	EVALUATES MOISTURE RESISTANCE OF THE DEVICE WHEN STORED FOR A LONG TERM AT HIGH TEMPERATURE AND HUMIDITY T _a = 65±5°C RH=90~95%RH TEST TIME=240± 2Hrs
	HIGH TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN HIGH TEMPERATURE T _a = 85±5°C(COB: T _a =65±5°C) TEST TIME=1000Hrs(-24Hrs, +72Hrs)
	LOW TEMPERATURE STORAGE	EVALUATES DEVICE DURABILITY FOR LONG TERM STORAGE IN LOW TEMPERATURE T _a = -35±5°C TEST TIME=1000Hrs(-24Hrs, +72Hrs)
ENVIRONMENTAL TEST	TEMPERATURE CYCLING	EVALUATES RESISTANCE OF DEVICE AT THERMAL STRESSES OR EXPANSION AND CONTRACTION 85°C ~ 25°C ~ -35°C ~ 25°C 30min 5min 30min 5min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	THERMAL SHOCK	EVALUATES DEVICE STRUCTURE AND STRUCTURE AND MECHANICAL RESISTANCE WHEN SUDDENLY EXPOSED AT SERVE CHANGES 85±5°C ~ -35±5°C 10min 10min 10 CYCLES(COB: T _{hot} =65°C, T _{cold} =-25°C)
	SOLDERABILITY	EVALUATES SOLDERABILITY ON LEADS OF DEVICE T _{SOL} =230±5°C DWELL TIME=5±1sec.
	SOLDER RESISTANCE	EVALUATES RESISTANCE TO THERMAL STRESS CAUSED BY SOLDERING T _{SOL} =260±5°C DWELL TIME=10±1sec.

Packing method A:

110 pcs / Red Expandable Polyethylene.

660 pcs / Box(360*175*130mm).

3960 pcs / Carton(550*380*280mm).

Packing method B:

16 pcs / IC Tube.

1120 pcs / Box(537*175*125mm).

4480 pcs / Carton(550*380*280mm).